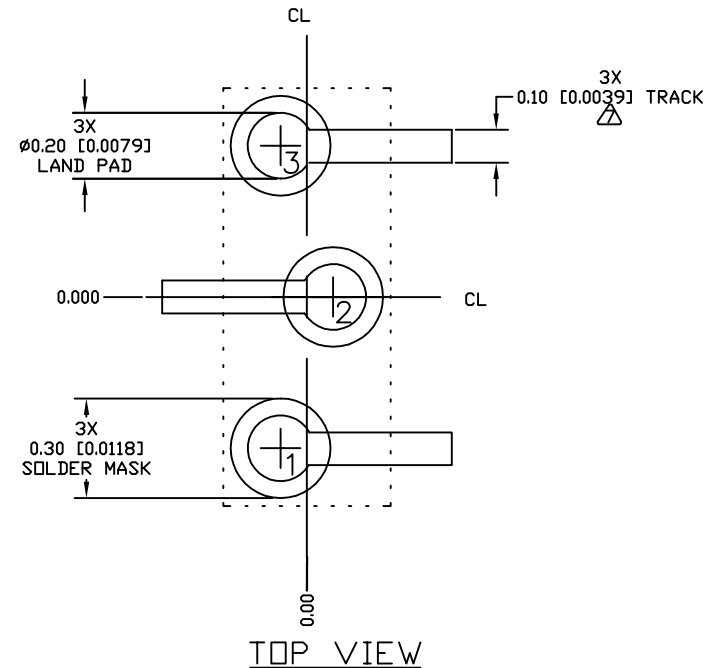
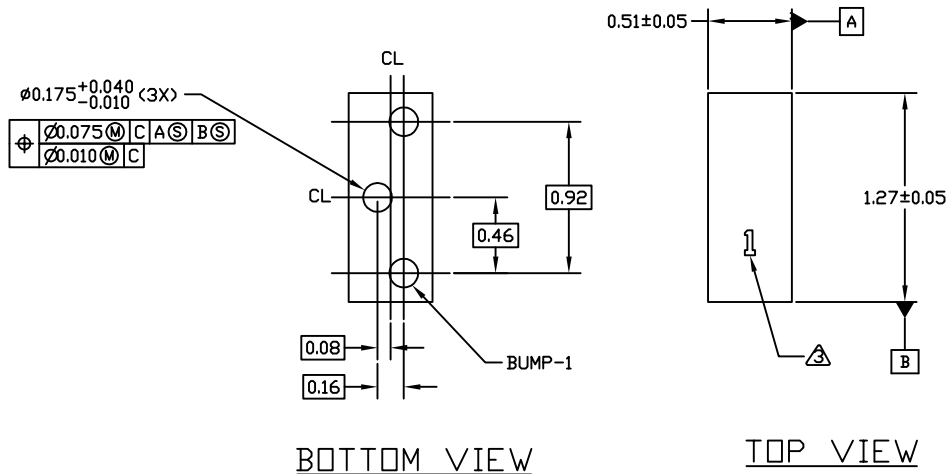


TABLE 1. LAND PAD CONNECTIONS AND CENTER COORDINATES		MILLIMETERS		INCH	
NUMBER	NAME	X	Y	X	Y
1	VO	-0.08	-0.46	-0.0031	-0.0181
2	VDD	0.08	0	0.0031	0
3	GND	-0.08	0.46	-0.0031	0.0181



RECOMMENDED SUBSTRATE
LAND PATTERN (NSMD)

NOTES:

- ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
- MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10-0131.
- LASER MARK ON PIN-1 END OF PACKAGE
- LANDING PAD NOT DEFINED BY SOLDER MASK (NSMD); SOLDER PASTE RECOMMENDED
- FOR PAD CONNECTIONS AND COORDINATES, SEE TABLE 1
- BUMP MATERIAL: 95 Pb / 5 Sn
- TRACK DIRECTIONS SHOWN MINIMIZE POSSIBILITY OF SOLDER PASTE TOUCHING DIE EDGE WHEN THICKER STENCILS ARE USED
- ALL DIMENSIONS APPLY TO LEADED (-), PKG. CODES ONLY.
- PACKAGE CODE: BF311-1

-DRAWING NOT TO SCALE-

MAXIM			
TITLE: PACKAGE OUTLINE, 3 BUMPS FLIP CHIP, 0.51x1.27x0.33mm, 0.460mm PITCH			
APPROVAL	DOCUMENT CONTROL NO. 21-0279	REV. B	1/1